Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.6 EP)
Lead Count	24
Terminal Finish	100 Sn
MS Number	MS011309A

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.55E-02	87.00	870000	45.36	453595
Thermosets	Epoxy & Phenol Resin	628290-34-6	2.23E-03	12.50	125000	6.52	65172
Other inorganic materials	Carbon black	1333-86-4	8.92E-05	0.50	5000	0.26	2607
Subtotal			1.78E-02	100.00	1000000	52.14	521374

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.31 E-02	97.5	975000	38.39	383937
Copper & its alloys	Iron	7439-89-6	3.16 E-04	2.35	23500	0.93	9254
Copper & its alloys	Zinc	7440-66-6	1.62 E-05	0.12	1200	0.05	473
Copper & its alloys	Phosphorus	7723-14-0	4.04 E-06	0.03	300	0.01	118
Subtotal			1.35 E-02	100.00	1000000	39.38	393781

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.47 E-04	100.0	1000000	1.60	15982

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	9.05 E-04	100.0	1000000	2.65	26462

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	6.13 E-05	97.70	977000	0.18	1792
Precious metals	Palladium	7440-05-3	1.44 E-06	2.30	23000	0.00	42
Subtotal			6.27 E-05	100.00	1000000	0.18	1834

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.07 E-03	100.00	1000000	3.12	31178

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.71 E-04	84.00	840000	0.79	7923
Other organic materials	Epoxy Resin	9003-36-5 / 30583-72-3	3.87 E-05	12.00	120000	0.11	1132
Other organic materials	t-butyl phenyl glycidyl ether	3101-60-8	6.45 E-06	2.00	20000	0.02	189
Other organic materials	Phenolic hardener	92-88-6 / 26834-02-6	4.84 E-06	1.50	15000	0.01	141
Other organic materials	Butyl cellosolve acetate	112-07-2	1.61 E-06	0.50	5000	0.005	47
Subtotal			3.23 E-04	100.0	1000000	0.94	9432

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.42 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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